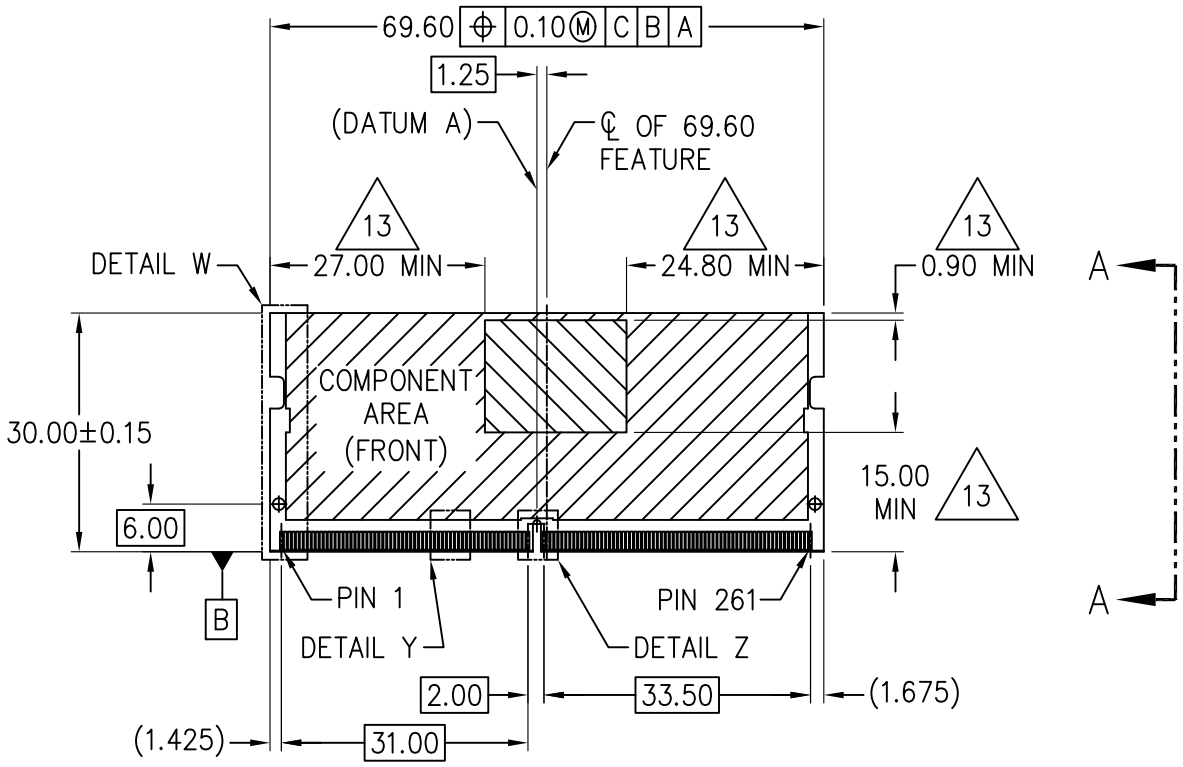

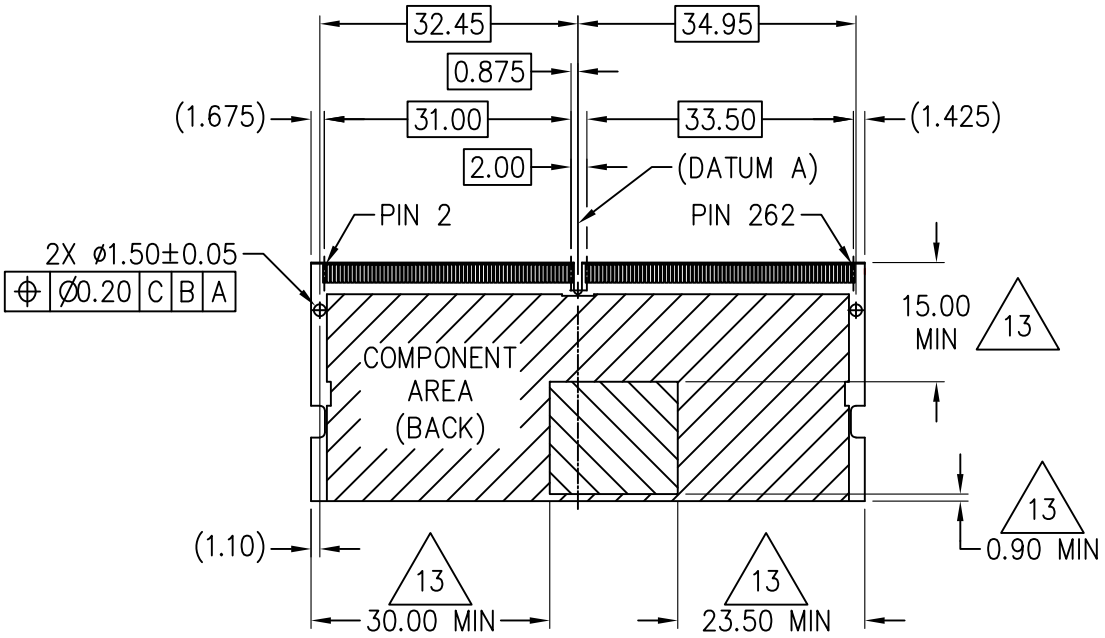

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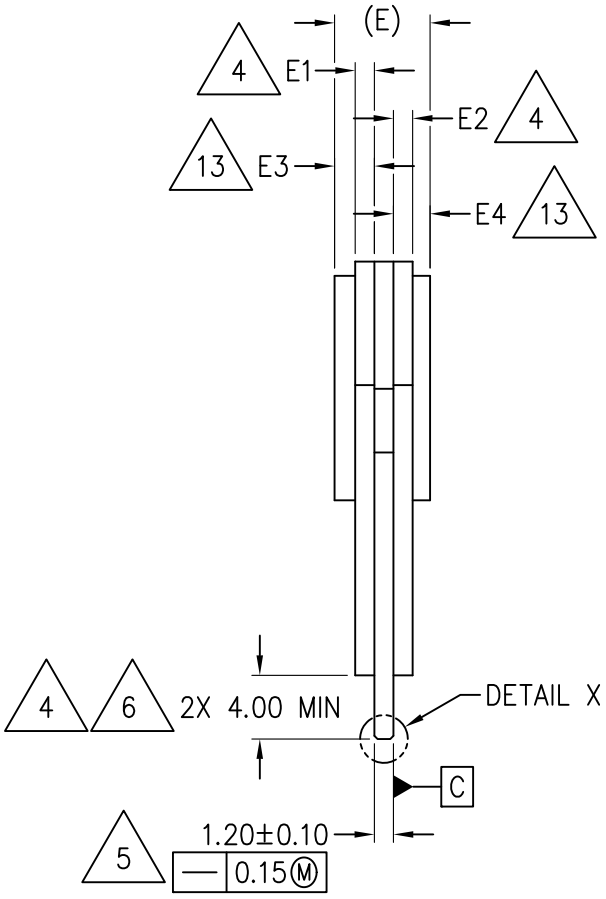
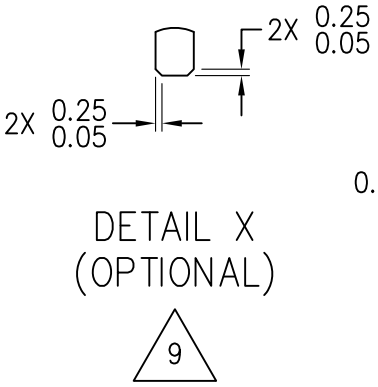
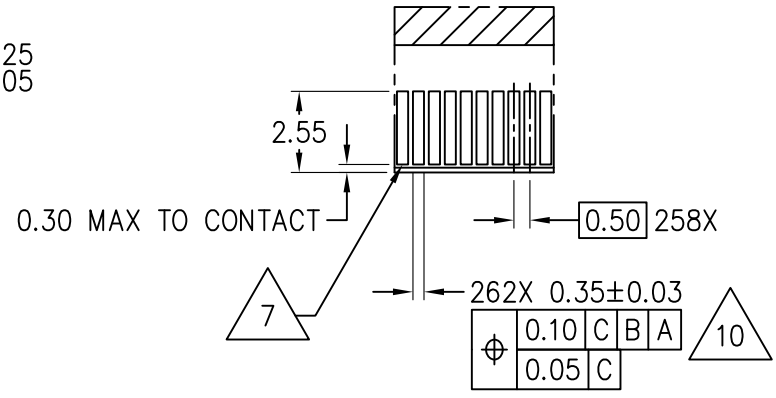
TITLE	PACKAGE DESIGNATOR	NUMBER	ISSUE	DATE	SHEET
262 PIN DDR5 SODIMM, 0.50MM PITCH PACKAGE	PDMA-N262-I0p5-R69p6x3p7Z30p15 R2p55x0p35	MO-337	B	FEB 2022	1 OF 9



VIEW A–A

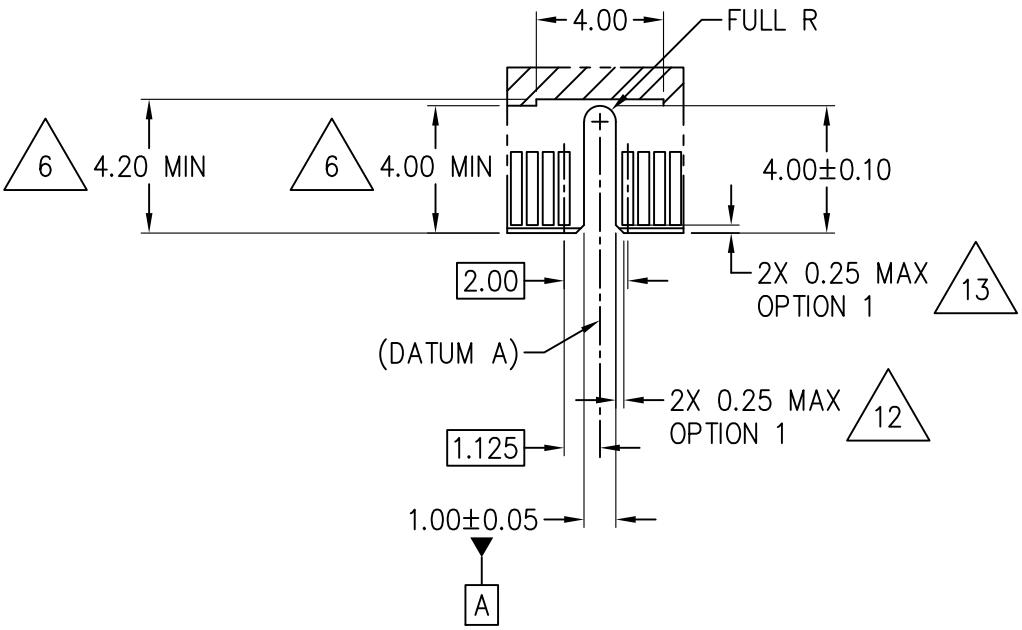


DETAIL X
(OPTIONAL)

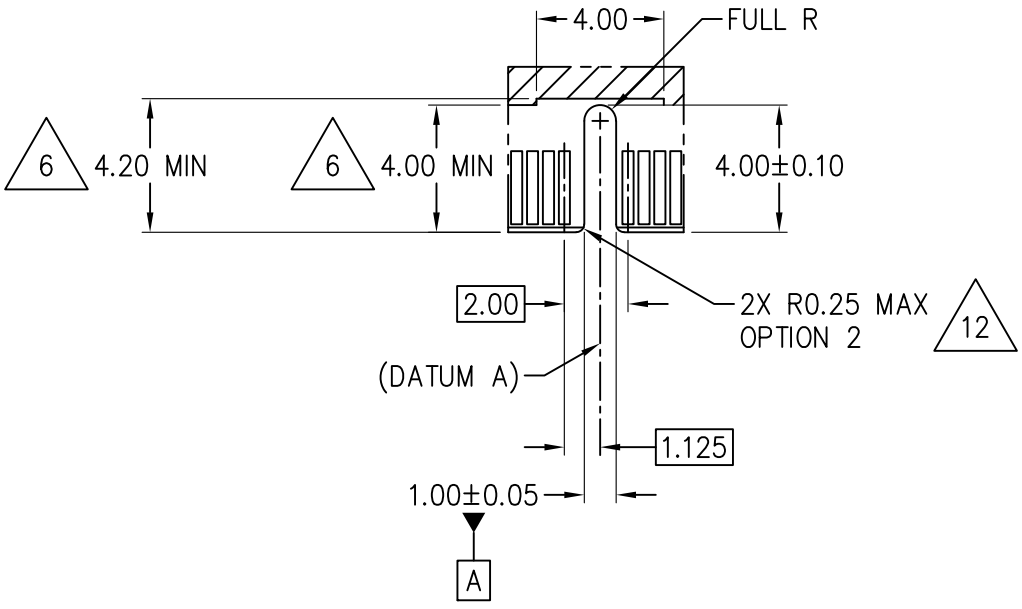


DETAIL Y

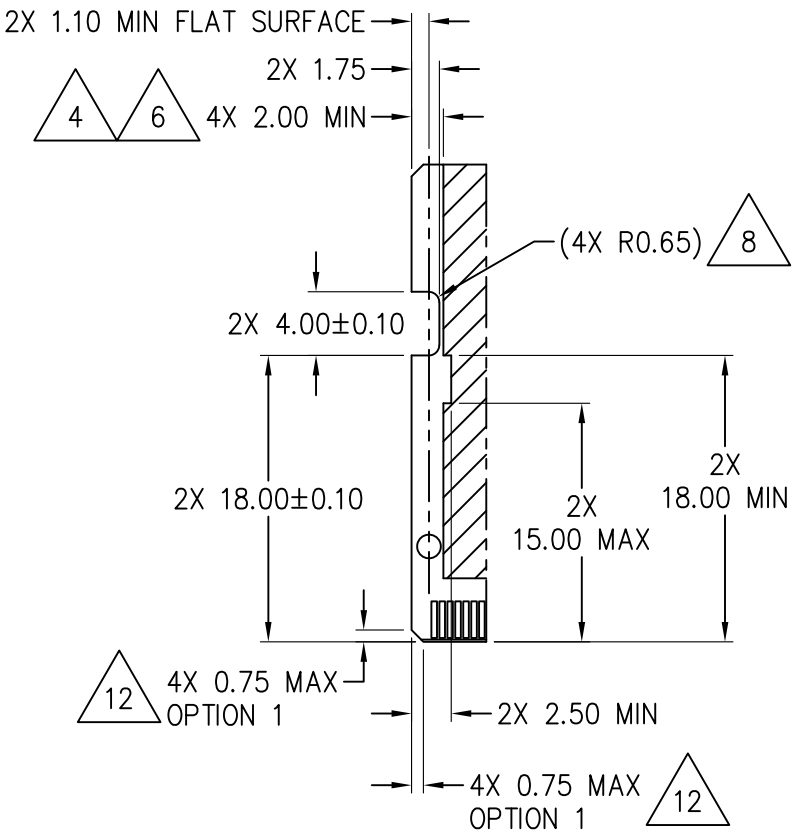
JEDEC SOLID STATE PRODUCT OUTLINE Copyright © 2022 JEDEC	TITLE 262 PIN DDR5 SODIMM, 0.50MM PITCH PACKAGE	NUMBER MO-337	ISSUE B	DATE FEB 2022	SHEET 2 OF 9

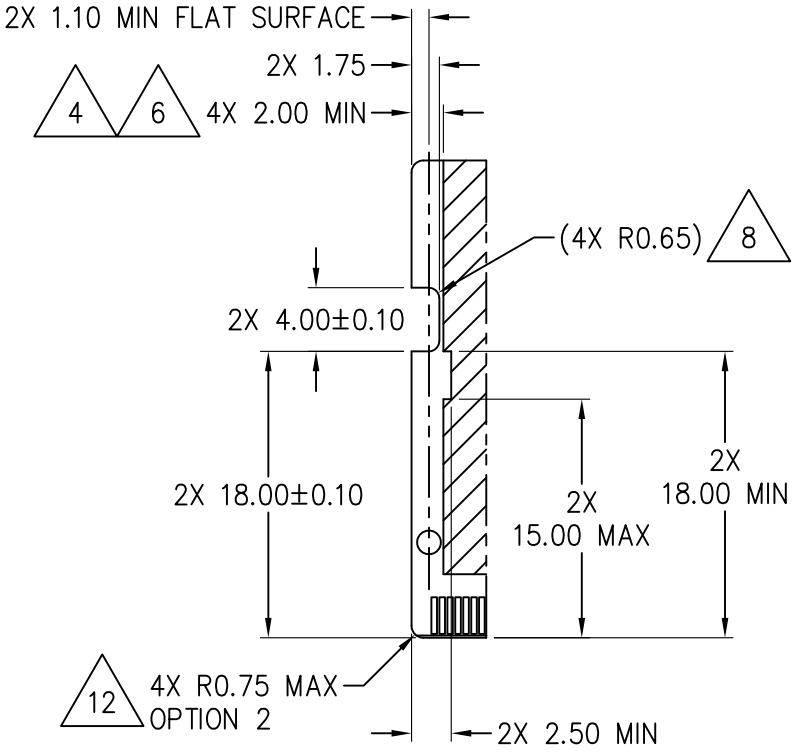


DETAIL Z



DETAIL Z





DETAIL W

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VARIATION Xxxx IS USED FOR MODULE HEIGHT.
THIS MICROELECTRONIC ASSEMBLY HAS ONE MODULE HEIGHT AND THEREFORE THIS VARIATION IS NOT USED.

TABLE 1

MODULE THICKNESS VARIATIONS			
VARIATION ▶	xAxx	xBxx	xCxx
SYMBOL ▼	MAX	MAX	MAX
(E)	3.70	---	---
E1 (FRONT)	1.00	---	---
E2 (BACK)	1.00	---	---
E3 (FRONT)	1.30		
E4 (BACK)	1.10		
NOTES	4		
REF	14-192, 14-207		
ISSUE	B		

VARIATION xxXx IS USED FOR PLATING AND FOUND IN NOTE 10.

VARIATION xxxX IS USED FOR ALIGNMENT KEY LOCATION.
THIS MICROELECTRONIC ASSEMBLY HAS ONE ALIGNMENT KEY LOCATION AND THEREFORE THIS VARIATION IS NOT USED.

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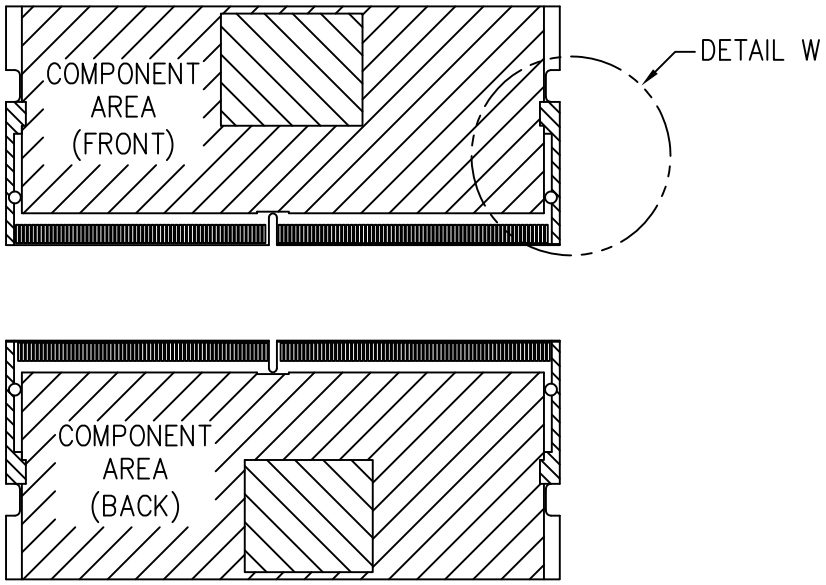
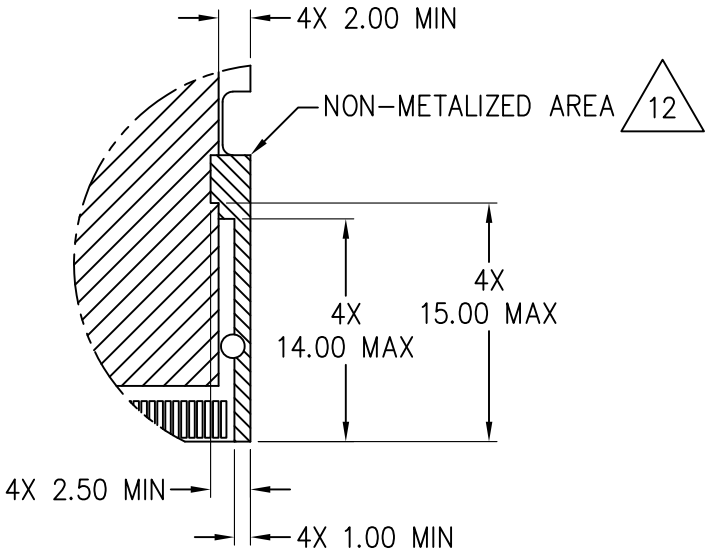
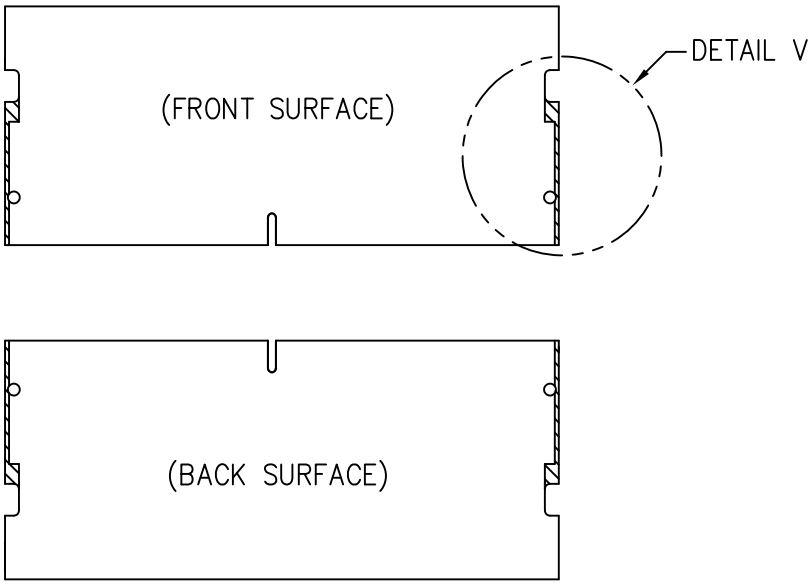
NON-METALIZED DEFINITION OUTER LAYERS
OPTIONAL CHAMFER/RADII DETAIL NOT SHOWN

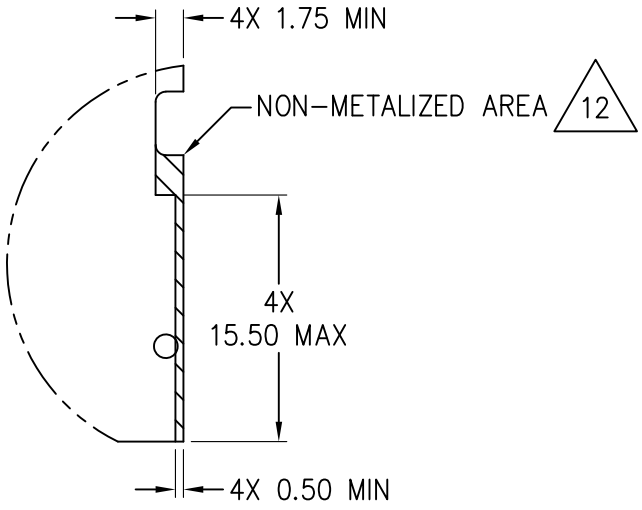




DETAIL W

NON-METALIZED DEFINITION ALL INNER LAYERS
OPTIONAL CHAMFER/RADII DETAIL NOT SHOWN





DETAIL V

JEDEC SOLID STATE PRODUCT OUTLINE	TITLE	NUMBER	ISSUE	DATE	SHEET
Copyright © 2022 JEDEC	262 PIN DDR5 SODIMM, 0.50MM PITCH PACKAGE	MO-337	B	FEB 2022	7 OF 9

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5–2009.

2. TOLERANCES ON ALL DIMENSIONS ±0.15 UNLESS OTHERWISE SPECIFIED.

3. ALL DIMENSIONS ARE MM.

4 DIMENSIONS APPLICABLE WHEN COMPONENTS MOUNTED ON BOTH SIDES. PCB THICKNESS NOT TO BE EXCEEDED OUTSIDE OF COMPONENT AREA.

5 CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALIZED AREAS.

6 BORDER OF COMPONENT AREA.

7 EDGE OF CONTACT PADS AND TIE BARS, IF PRESENT, SHALL BE FREE OF BURRS.

8 THE (R0.65) DIMENSION IS FOR REFERENCE ONLY. THE 1.10MM MIN FLAT SURFACE AND THE 2X 1.75 CONTROL THE FEATURE.

APPLICATION NOTES:

9 THE ADDITION OF THIS BEVEL IS A FABRICATION OPTION AND IS NOT REQUIRED. THE BEVEL IS NOT TO HIT THE PLATED CONTACTS.

10 RECOMMENDED PLATING FOR CONTACT PADS ARE:
1) VARIATION xxAx: GOLD PLATING 0.76 MICROMETERS MINIMUM OVER 2.00 MICROMETERS MINIMUM NICKEL.
2) VARIATION xxBx: GOLD PLATING 0.05 MICROMETERS MINIMUM OVER 0.25 MICROMETERS MINIMUM PALLADIUM OVER 2.00 MICROMETERS MINIMUM NICKEL
3) VARIATION xxCx: GOLD PLATING 0.05 MICROMETERS MINIMUM OVER 2.00 MICROMETERS MINIMUM NICKEL.
MODULE PLATING RECOMMENDATIONS TESTED PER INDUSTRY STANDARD EIA 364–1000. RELIABILITY TESTING REQUIRES TEST MODULE, CONNECTOR, AND IDENTIFICATION OF TEST CONDITIONS.

11 'METALIZED' IS DEFINED AS ANY METAL SURFACE THAT HAS A RETURN PATH TO POWER SUPPLY OR GROUND, THROUGH A COMPONENT OR CONDUCTIVE PLANE VCC OR VDD, BLIND OR PLATED THROUGH HOLE (PTH), AS WELL AS NARROW OR WIDE TRACES. ANY SURFACE METALS SUCH AS CONNECTOR PIN IDENTIFICATION, PCB VENDER CODE, ETC. THAT DO NOT HAVE A METALS AS A RETURN PATH ARE ACCEPTABLE. 'NON–METALIZED' IS DEFINED AS THE OPPOSITE TO 'METALIZED' AND DOES NOT INCLUDE ANY METAL OR CONDUCTIVE ELEMENTS THAT MAY CAUSE ELECTRICAL SHORT CIRCUIT. HOWEVER, ANY SURFACE METALS SUCH AS CONNECTOR PIN IDENTIFICATION, PCB VENDOR NAME OR CODE, ETC. THAT DOES NOT HAVE CONDUCTIVE RETURN PATH TO VCC OR VDD IS ACCEPTABLE.

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12 OPTIONAL CHAMFER OR RADIUS.

13 THE DIMENSION DEFINES THE BOUNDARY OF COMPONENTS, SUCH AS CAPACITORS AND INDUCTORS.

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STP (3D) FILE RECORD

3D FILE NAMES MAY EXCEED LENGTH REQUIREMENTS FOR SOME SOFTWARE TOOLS.

STP FILE NAME	DATE	ITEM NUMBER
MO-337A_PDMA-N262-I0p5-R69p6x3p7Z30p15R2p55x0p35	APR 2019	14-192
MO-337B_PDMA-N262-I0p5-R69p6x3p7Z30p15R2p55x0p35	FEB 2022	14-207

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MICRON TECHNOLOGY INC.
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CHANGE RECORD

IF THE CHANGE INVOLVES ANY WORDS ADDED OR DELETED (EXCLUDING DELETION OF ACCIDENTALLY REPEATED WORDS), THE CHANGE IS TO BE INCLUDED BELOW. PUNCTUATION CHANGES MAY OR MAY NOT BE INCLUDED.

INITIAL ISSUE: A	DATE: APRIL 2019	ITEM NUMBER: 14–192

CHANGE RECORD HISTORY:

ISSUE: B	DATE: FEBRUARY 2022	ITEM NUMBER: 14–207

LOCATION	CHANGED FROM:	CHANGED TO:
SHEET 1		ADD COMPONENT AREA AND DIMENSIONS
		MOVED 32.45 AND 34.95 DIM
	⌖ | Ø0.10Ⓜ | C | B | A	⌖ | Ø0.20Ⓜ | C | B | A
SHEET 2		ADDED E3 AND E4
	2X 0.35 0.05	2X 0.25 0.05
SHEET 5		ADDED VARIATION NOTES
	VIRATION: Axxx, Bxxx, Cxxx	VARIATION: xAxx, xBxx, xCxx
	E1 1.20	E1 (FRONT) 1.00
	E2 1.20	E2 (BACK) 1.00
		ADDED E3 AND E4
SHEET 6		UPDATED COMPONENT AREA
SHEET 8		DELETED NOTE 4
		DECREASE NOTE NUMBER BY 1 FROM 5 ON.
SHEET 9		ADDED NOTE 13
SHEET ii		NEW SHEET

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